

## CALL FOR PAPERS

35th Annual Semiconductor Thermal Measurement, Modeling and Management Symposium March 18-22, 2019 DoubleTree by Hilton, San Jose, CA USA

SEMI-THERM is an international symposium dedicated to the thermal management and characterization of electronic components and systems. The symposium fosters the exchange of knowledge between thermal engineers, professionals and leading experts from industry as well as the exchange of information on the latest academic and industrial advances in electronics thermal management.

## **Topics**

Component to System Level Thermal Management	Nanotechnology & Novel Materials	Multi-physics Modeling and Characterization of Products and Processes	Packaging Materials
Computational Fluid Dynamics (CFD)	Air Mover Technologies with Low Acoustics	Mechanical Modeling, Simulations and Characterization	Multi-Physics Based Reliability, including Accelerated Testing
Advanced Cooling Techniques/Technology	Energy Harvesting Materials Thermo Electronics	Roadmaps, Specifications and Traditional Cooling Limits	Characterization and Standardization of Material Property Measurements

## **Applications**

- Processors, ICs, and Memory
- 3-D packaging
- Internet of Things, Wireless, Network, Computing Systems
- Data Centers
- Portable and Consumer Electronics
- Power Electronics, Harsh Environments
- Commercial, Defense, and Aerospace Systems
- Drones and Digital Imaging

- Solid-State Lighting, Solid State Energy Generation/Cooling
- Medical and Biomedical electronics
- Instrumentation and Controls
- Micro and Nano-scale devices, MEMS and sensors
- Alternative and Renewable Energy
- Wearable and Portable Devices

## **Symposium Highlights**

- Technical Sessions Extended abstracts, peer reviewed papers, presentation only sessions, dialog sessions
- Technical Short courses (March 18, 2019)
- Embedded tutorials, technical vendor workshops, "How To" courses, Product Tear Downs, Mobile App Development Challenge. Panel Discussions on current thermal technologies
- Exhibits: Cooling technologies, Air movers, Test and Measurement Equipment, CFD simulation software, Thermal materials

To submit a peer-reviewed paper: Submit a full manuscript to be peer reviewed by selected SEMI-THERM Technical Committee members .

**To submit an extended abstract:** Describe the scope, contents, key results, findings and conclusions. The abstract should be 2 to 5 pages and supported by figures, tables and references as appropriate. Abstracts must demonstrate high technical quality and originality.

**To submit a presentation only power point:** Presentational only abstract (no full paper required) Abstracts must demonstrate high technical quality, originality and potential impacts and will be reviewed by selected SEMI-THERM committee members.

Peer reviewed submission date	Extended and Presentation only Abstracts submission date	Photo-Ready Full Manuscript submission date
Oct 12 ,2018	Oct 12, 2018	Jan 18, 2019

Upload your paper electronically in RTF, DOC or PDF formats at <a href="www.semi-therm.org">www.semi-therm.org</a>.

For further information please contact the Program Chair
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\*\* All authors qualify for reduced symposium rates \*\*